

Bill of Materials

	SCM	SCC	Remarks
Die Attach	Ablestik 3230	Ablestik 3230	Same BOM
Wire type	Gold MKE UR2	Gold MKE UR2	
Mold Compound	Sumitomo G770	Sumitomo G770	
Lead Finish	Matte Sn	Matte Sn	

Qualification Results for LFCSP Package at STATS ChipPAC China (SCC)

QUALIFICATION RESULT			
Test	Conditions	Sample Size	Result
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	3 x 77	PASS
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 x 77	PASS
Autoclave (AC)*	JEDEC <i>JESD22-A102</i>	3 x 77	PASS
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	3 x 11	PASS
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	1 x 77	PASS
Field Induced Charged Device Model (FICDM)	JEDEC <i>JESD22-C101</i>	3/Voltage	PASS ±1250V

*Preconditioned per JEDEC/IPC J-STD-020

Test Correlation Results

<u>FG Part Number</u>	<u>Test Correlation Results</u>
AD71133ACPZ	Pass
AD71133ACPZ-RL	Pass
AD71135ACPZ	Pass
AD71135ACPZ-RL	Pass
AD71157ACPZ	Pass
AD71157ACPZ-RL	Pass
ADE7978ACPZ	Pass
ADE7978ACPZ-RL	Pass
ADP1050ACPZ-R7	Pass
ADP1050ACPZ-RL	Pass
ADP1055ACPZ-R7	Pass
ADP1055ACPZ-RL	Pass
ADP2311ACPZ-1-R7	Pass
ADP2311ACPZ-2-R7	Pass
ADP2311ACPZ-3-R7	Pass
ADP2311ACPZ-4-R7	Pass